IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1					Form Type <sup>3</sup> Distribute						neous Materi	als and M	fg Infor	mation		
Supplier	Information															
Company	name*	Company unique ID			Ţ	Unique ID Authority					Response Date*					
onsemi												2023-06-08				
Contact N	ame	Title - Contact			1	Phone - Contact*					Email - Contact*					
Product-I	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
Authorize	d Representative*	Title - Representative			1	Phone - Representative*					Email - Representative*					
Product-I	Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date Version		ersion	Manufacturing Site			Weight*	k	UOM	Unit Type
		FOD817D		OSD 4PB TR T&R			2023-06-08			LITEONFG		2	224.155		mg	Each
Manufa	cturing Proccess Informat	tion						<u> </u>		,						
	Terminal Plating / Grid Array Material Termi			rminal Base Alloy J-STD-020 MSL I		Rating	Peak Process Body Temper		ody Temperat	ature Max Time at Peak Ten		Temperat	ure N	umber of	Reflow Cycle	es
Matte Tin (Sn) - annealed CU			U Alloy 1			<b>260</b> C		C	30 seco		secon	ds 3				
Comments																
evel 1 - m	aximum time at peak temperatu	re during sol	dering is 10-3	0 seconds												
or more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	0.74	mg	Supplier	Filler (SiO2)	68909-20-6		0.148	mg
			Supplier	Dimethyl Siloxane	68083-19-2		0.592	mg
Die	0.099	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.033	mg
			Supplier	Silicon (Si)	7440-21-3		0.066	mg
Die Attach	0.085	mg	Supplier	Silver (Ag)	7440-22-4		0.0697	mg
			Supplier	Dicyandiamine	461-58-5		0.0009	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0145	mg
Lead Frame	55.77	mg	Supplier	Sulfur (S)	7704-34-9		0.0084	mg
			Supplier	Carbon (C)	7440-44-0		0.0558	mg
			Supplier	Silver (Ag)	7440-22-4		0.0084	mg
			Supplier	Manganese (Mn)	7439-96-5		0.1394	mg
			Supplier	Silicon (Si)	7440-21-3		0.0084	mg
			Supplier	Iron (Fe)	7439-89-6		55.5246	mg
			Supplier	Copper (Cu)	7440-50-8		0.0167	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0084	mg
Mold Compound-Black	100.0		В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		2	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		17	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		3	mg
			Supplier	Carbon Black (C)	1333-86-4		1	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		70	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		7	mg
Mold Compound-White	63.2	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		18.96	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		44.24	mg
Plating	4.21	mg	Supplier	Tin (Sn)	7440-31-5		4.21	mg
Wire Bond - Au	0.051	mg	Supplier	Gold (Au)	7440-57-5		0.051	mg